Chinastandards.org

ICS 31.200
CCS L56

SJ

# INDUSTRY STANDARD OF THE PEOPLE'S REPUBLIC OF CHINA

# SJ 21553-2020

## Three-dimensional heterogeneous integrated fine-pitch micro-bump production technology requirements

三维异构集成细间距微凸点制作工艺技术要求

**(English Translation)**

**Implemented on: August 1, 2020**

**Issued by: Ministry of Industry and Information Technology**

Preview: page 1 of 3 shown, 9 in the full document. Complete English PDF, instant download:
https://chinastandards.org/standards/sj-21553-2020

Chinastandards.org

# Table of Contents

[Preview only]
1 Scope
2 Normative References
2.1 Terms
3 Terms and Definitions
4 Overview
4.1 General requirements
5 Technical Requirements
6 Calibration conditions
6.1 Environmental conditions
6.2 Measurement standards and other equipment
7 Calibration items and calibration methods
7.1 Calibration Items
7.2 Calibration method
8 Expression of calibration results
9 Recalibration interval

## 1 Foreword

SJ 21553-2020 was issued by Ministry of Industry and Information Technology on 3 June 2020 and has been in force since 1 August 2020.

The SJ prefix, without a suffix, marks a mandatory standard: within its scope, compliance is required.

The document runs to 9 pages in English translation.

## 2 Scope Preview

SJ 21553-2020 falls under ICS 31.200, in the field of electronics.

This catalogue holds 133 other SJ standards in that field.

In this catalogue, SJ standards carry edition years from 1965 to 2021.



Preview: page 2 of 3 shown, 9 in the full document. Complete English PDF, instant download:
https://chinastandards.org/standards/sj-21553-2020

## 3 About this standard

Sector: Electronics Industry Standard

Issued by: Ministry of Industry and Information Technology

English translation: about 9 pages (approximate)

Chinese original: about 13,183 characters

## 4 Related standards

Standards on related subjects:

SJ/T 11890-2023 - Design requirement of energy conservation for LED displays

SJ/T 11891-2023 - Energy efficiency measurement method for LED displays

GB/T 35010.6-2018 - Semiconductor die products -- Part 6: Requirements for concerning thermal simulation

SJ/T 12035-2025 - Artificial intelligence chip - Testing metrics and methods for edge-side deep learning chips

SJ/T 12034-2025 - Artificial intelligence chip - Testing metrics and methods for edge-side deep learning chips

SJ 21550-2020 - High-speed signal transmission performance test method of microelectronic package ceramic housing

## 5 Classification and status

International classification (ICS): 31.200

Chinese Standard Classification (CCS): L 56

Prefix SJ: mandatory standard.



Preview: page 3 of 3 shown, 9 in the full document. Complete English PDF, instant download:
https://chinastandards.org/standards/sj-21553-2020